

# Mounting structure for electronic component e.g. ball grid array (BGA) package used in a portable apparatus

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**Novelty:** The mounting structure has bumps (7) arranged in an array. Each bump consists of an elastic section (7a) and an electrically conductive section (7b).

**Detailed Description:** The bumps are formed in array sequence on the back side of an electronic component (1). The electronic component is joined to a mounting substrate (3) by electrically connecting the bumps to the electrodes (2) on the mounting substrate. The electrodes are arranged in an array corresponding to the bumps.

**Use:** For an electronic component e.g. a BGA used in a portable apparatus.

**Advantage:** Prevents contact failure in a BGA package and multilayer printed wiring board (PWB) caused by external shock.

**Description of Drawing(s):** The figure shows a cross-sectional model diagram when mounting the BGA package on a multilayer PWB.

Bumps 7

Elastic section 7a

Electrically conductive section 7b

(Opp Dwg.No.1/2)

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